

<b>FORM PTO-1449</b> (Modified) <b>MAY 07 2001</b> PATENT & TRADEMARK OFFICE (37 CFR 1.98(b))	<b>U.S. DEPARTMENT OF COMMERCE</b> <b>PATENT AND TRADEMARK OFFICE</b>		POCKET NO. <b>FORM 2132 (P129)</b>	APPLICATION NO. <b>09/819,181</b>
	<b>INFORMATION DISCLOSURE</b> <b>STATEMENT BY APPLICANT</b>			
	(Use several sheets if necessary)		APPLICANT <b>Charles A. MILLER</b>	FILING DATE <b>March 27, 2001</b>

**U.S. PATENT DOCUMENTS**

EXAM INIT	PATENT NUMBER	ISSUE DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE

**FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION**

EXAM INIT	DOCUMENT NUMBER	PUBL. DATE	COUNTRY OR PAT. OFFICE	CLASS	SUB CLASS	TRANS.	
						Y	N

**OTHER DOCUMENTS** (Including Author, Title, Date, Relevant Pages, Place of Publication)

<i>cc</i>	Gregus, Jeffrey A., Maureen Y. Lau, Yinon Degani and King L. Tai, "Chip-Scale Modules for High-Level Integration in the 21st Century," <u>BELL LABS TECHNICAL JOURNAL</u> , July-September 1998, pages 116-124
<i>I</i>	Mehra, Amit, Zin Zhang, Arturo A. Ayón, Ian A. Waitz, Martin A. Schmidt, "Through-wafer Electrical Interconnect for Multilevel Microelectromechanical System Devices," <u>J. VAC. SCI. TECHNOL. B 18(5)</u> , Sep/Oct 2000, pages 2583-2589
<i>I</i>	"Through-Wafer Electrical Interconnects Compatible With Standard Semiconductor Processing," <u>mhtml:file://C:\TEMP\Eugene Chow hlton head.mht</u> , September 25, 2000
<i>I</i>	Murphy, Tom, "Tru-Si Technologies Makes Wafer Stacking a Possibility," <u>ELECTRONIC NEWS</u> (1991), December 6, 1999
<i>I</i>	"2D Microcantilever Arrays with Through-Wafer Interconnects," <u>http://www.stanford.edu/~emc/2dpicts.html</u> , December 14, 2000
<i>cc</i>	"Employment of the Deep Plasma Silicon Etching for the Production of New Microfluidic Components," <u>http://222.tu-dresden.de/eti/m/english/research/hlt/ihm_eng/fo_pro_e/fra_e012.html</u> , December 15, 2000
<i>cc</i>	"Advanced Silicon Etch (ASE)", <u>http://www.stsystems.com/ase.html</u> , January 15, 2001

EXAMINER <i>cc</i>	DATE CONSIDERED <i>2/12/02</i>
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EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.